

LINEAR TECHNOLOGY MATERIALS DECLARATION

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(Engineering Calculation)

SOT-223

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TOTAL MASS (g) : 0.11697

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|--------------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|---------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.002855 | 1000000 | 24407.8886719 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.062693 | 975000 | 535973.25 | | |
| | | Iron (Fe) | 7439-89-6 | 0.001543 | 24000 | 13191.3720703 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000019 | 300 | 162.434265137 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000045 | 700 | 384.712768555 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.064300 | 1000000 | 549711.75 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.001609 | 1000000 | 13758.953125 | | |
| | | External Plating Total: | | | | 0.001609 | 1000000 | 13758.953125 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000514 | 1000000 | 4394.27490234 | | |
| Internal Plating Total: | | | | 0.000514 | 1000000 | 4394.27490234 | | |
| Die Attach | Solder Wire Dia 0.3mm *100m 95Pb/5Sn | Silver (Ag) | 7440-22-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000077 | 50000 | 658.286193848 | | |
| | | Lead (Pb) | 7439-92-1 | 0.001466 | 950000 | 12533.0859375 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000000 | 0 | 0 | | |
| Die Attach Total: | | | | 0.001543 | 1000000 | 13191.3720703 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.004738 | 103000 | 40505.9804688 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.041170 | 895000 | 351969.40625 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000092 | 2000 | 786.523864746 | | |
| | | Encapsulation Total: | | | | 0.046000 | 1000000 | 393261.90625 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000149 | 1000000 | 1273.82666016 | | |
| | | | | | TOTAL MASS (g) : | 0.11697 | | |